

## Double-Sided & Multi-Layered

Items		Mass	Sample
Layers		2-68L	Up to 120L
Max. Board Thickness		10mm(394mil)	14mm(551mil)
Min. Width/Space	Inner Layer	50/50um	40/40um
	Outer Layer	65/65um	50/50um
Registration	Same Core	±25um	±20um
	Layer to Layer	±4.5mil	±4mil
Max. Copper Thickness		6oz	30oz
Min. Drill Hole Diameter	Mechanical	≥0.15mm(6mil)	≥0.1mm(4mil)
	Laser	0.1-0.35mm	0.05-0.35mm
Max. Size (Finish Size)	Line-card	850mmX570mm	1000mmX570mm
	Backplane	1250mmX570mm	1320mmX570mm
Aspect Ratio (Finish Hole)	Line-card	20:1	27:1
	Backplane	25:1	32:1
Material	FR4	EM827, 370HR, S1000-2, IT180A, EM825, IT158, S1000 / S1155, R1566W, EM285, TU862HF,EM370D,IT170GRA1, Autolad1,Autolad3,NP175FBH,IT170GT,H175HF	
	High Speed	Megtron4, TU872SLK, FR408HR,N4000-13 Series, S7439C,TU863+, Megtron6, MW2000, IT968,EM891, Megtron7, MW4000,TU933,DS7409DVN,IT988GSE	
	High Frequency	Ro3003, Ro3006, Ro4350B, Ro4360G2, Ro4835, CLTE, Genclad, RF35, FastRise27,TLY series,AD series,RT6002	
	Others	Polyimide, Tk, LCP, BT, C-ply, Fradflex, Omega , ZBC2000,ST115	
Surface Finish		HASL, ENIG, Immersion Tin, OSP, Immersion Silver, Electroplating Hard Gold/Soft Gold, Gold Finger, Selective OSP, ENEPIG 20	